

**DELIVERING BREAKTHROUGH IDEAS TO INDUSTRY**



CMMT Director  
Prof. Farrokh Ayazi

**Center for MEMS and Microsystems Technologies (CMMT) &  
Packaging Research Center (PRC) of**

**Georgia Tech**

*invite you to attend*

**MEMS PACKAGING CONSORTIUM  
OPEN HOUSE**

**Monday, May 20, 2013 - MaRC Building Auditorium**

**1:00 p.m. - 6:30 p.m.**



PRC Director  
Prof. Rao Tummala

Two internationally-renowned research centers at Georgia Tech, **the Center for MEMS and Microsystems Technologies (CMMT) and the Packaging Research Center (PRC)** will host a joint industry consortium Open House in leading-edge MEMS Packaging R&D to address some of the biggest challenges in the Packaging of MEMS in consumer, medical and industrial applications.

**The GT MEMS Packaging research** focuses to bring synergy between MEMS devices and their package by means of understanding MEMS-Package Interactions (MPI) and focusing on MEMS-Package Integration (MPI) using low stress, low temperature sealing, interconnections, and assembly to improve performance, cost and reliability over current MEMS packaging approaches.

**Open House Agenda**

[Register Here](#)

- 1:00 PM Gathering in MaRC Building Auditorium**  
**1:00 - 1:15 PM** Vision and Strategy for MEMS Packaging Consortium at GA Tech: MPI – *Prof. Farrokh Ayazi & Prof. Rao Tummala*  
**1:15 - 1:30 PM** PRC Overview – *Prof. Rao Tummala*  
**1:30 - 2:00 PM** CMMT Overview – *Prof. Farrokh Ayazi*
- 2:10 - 4:00 PM MEMS Package Integration (MPI)**  
 MEMS Package Integration(MPI) Vision – *Prof. Farrokh Ayazi*  
 Low Cost Glass for MPI – *Dr. Venky Sundaram*
- MEMS Package Interactions**  
 Multi Domain Interactions between MEMS and Package – *Prof. Farrokh Ayazi*  
 Interconnections and sealing – *Dr. Vanessa Smet*  
 Modeling & Characterization – *Prof. Farrokh Ayazi*
- Consortium Model**  
 Cost of Membership, IP and Technology Transfer – *Mr. Sung Jin Kim*
- 4:00 - 5:00 PM Lab Tours**  
 PRC (MaRC Building)  
 NRC (Marcus Building)  
 MIRC (Pettit Building)
- 5:00 - 6:30 PM Reception in MaRC Building Atrium**

**Faculty and inter-disciplinary experts from both centers** work collaboratively with industry to improve the design, function and manufacturability of MEMS Packaging. **Questions about the MEMS Packaging Joint Consortium?** Contact Prof. Farrokh Ayazi at [ayazi@gatech.edu](mailto:ayazi@gatech.edu) or Prof. Rao Tummala at [rao.tummala@prc.gatech.edu](mailto:rao.tummala@prc.gatech.edu)

**MEMS PACKAGING**